

Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-10 (cancelled)

Claim 11 (currently amended): A method for removing coatings from a plurality of substrates comprising the steps of:

~~providing~~ providing a substrate carrier containing a plurality of substrates;

providing a tank containing a liquid chemical;

placing a gas distribution plate on bottom of said tank, said gas distribution plate having a groove for guiding a flexible tubing;

drilling a linear array of holes in said flexible tubing;

connecting said flexible tubing to a pressure regulated gas supply;

positioning said substrate carrier on said gas distribution plate so that a linear array of gas bubbles flowing upwards scrub surfaces between each substrate.

Claim 12 (previously presented): The method according to claim 11 wherein a plurality of lines of gas bubbles forms patterns that correspond to each substrate contained in said substrate carrier.

Claim 13 (original): The method according to claim 11 wherein said pressure regulated gas supply is nitrogen gas.

Claim 14 (previously presented): The method according to claim 11 wherein a gas distribution plate and a flexible tubing are each compatible with aggressive chemicals used for removing residues in sidewalls that are coated with an organic material.

Claim 15 (currently amended): A method for stripping photoresist from a plurality of semiconductor wafers, comprising the steps of:

~~proving~~providing a wafer cassette containing a plurality of wafers;
providing a tank containing a photoresist stripping chemical;
providing a gas distribution plate and placing it on bottom of said tank, said gas distribution plate having a groove for guiding a flexible tubing;
drilling a linear array of holes in said guided flexible tubing;
connecting said flexible tubing to a pressure related gas supply; and
positioning said wafer cassette on said gas distribution plate so that a linear array of gas bubbles emanating from holes drilled in said flexible tubing, flow upwards, therein scrubbing the surfaces of each wafer.

Claim 16 (currently amended): The method according to claim 15 wherein said gas distribution plate ~~having~~has a gas distribution pattern for generating rows of gas bubbles, each row corresponding to a wafer position in said wafer cassette.

Claim 17 (cancelled)



Claim 18 (previously presented): The method according to claim 15 wherein a gas distribution plate and a flexible tubing are both compatible with aggressive chemicals for removing residues.

Claim 19 (previously presented): The method according to claim 15 wherein said pressure regulated gas supply is nitrogen gas.